

described stage of the fabrication procedure, before molding of said one of the holding discs 24, is established by clamping between fixedly spaced rigid plates 30 and 32 on which resilient material layers 34 and 36 are respectively disposed. To facilitate molding, a thin mold release film 38 is placed on the resilient layer 34 underlying the lower ends of the elements 20 within the uncured body of epoxy resin retained within the seal ring 22 under pressure as denoted by arrow 40 and a clamping pressure on the plate 32 as denoted by arrow 42. The thickness of the holding discs 24 is determined by the height of the seal ring 22. When one of such discs 24 is so formed upon full curing of the epoxy resin after 24 hours for example, the element bundle as shown in FIG. 5 is then rotated 180° and the same fabrication procedure is repeated to form another holding disc 24 at the other ends of the elements 20, not shown in FIG. 5, to complete bundling of the elements before transfer to the module 10 for assembly therein.

### **CLEAN VERSION OF AMENDMENTS**

#### **TO THE CLAIMS**

Rewrite claim 1 as follows:

1. In combination with a housing of a module enclosing a plurality of elongated filter processing membrane elements through which a contaminate-laden fluid is filtered; the improvement residing in: sealing means for establishing a sealed chamber within the module housing through which the contaminate-laden fluid is conducted externally of and along the filter processing membrane elements; holding means for positioning the elongated processing membrane elements within the sealed chamber in a bundled condition; and spacer means maintaining the bundled processing membrane elements in laterally spaced relation to each other throughout within the sealed chamber through which the contaminated-laden fluid is conducted